TECHNICAL SPEC FOR Stepper

System Model:

Canon FPA 3000 i5 SN 8032195

Tool has been shut down by Litho tech.

Electricity, cooling water, Vacuum and CCA are closed.

Cables between Main unit and power box are still connected, locking kit and demounting for transport to be provided by buyer.

Wafer size: 6 inch

Wafer type: Jeida flat

Chuck type: 6 inch pin chuck

Reticle changer type: (Canon standard?)

Inline right or left: left

Particle checker (PPC): Yes

Touch panel type: Canon standard

Options:

Reticle size: 6 inch

Reticle alignment: see specs below

Wafer alignment: see specs below

Auto focus:see specs below

Auto feeder: Yes

Wafer tilt:

Wafer feeder: Yes

Track interface: Yes, tool was used inline, interface is track part

Laser: Hene

Vintage: 2011

Missing/defective parts: none



MODEL	FPA-3000 i5	INSTALLATION CHECK LIST				
SN	8032195	START DATE	4/4/2011			
CUSTOMER	ON Semi	END DATE	8/11/2011			

	DESCRIPTION			UNIT	SPECIFICATION	
		DX	0.029			
	LENS DISTORTION (Normal)	DY	0.022	μm	≤ ± 0.04	
Σ	Charles I Alberta Com	Uniformity	2.2	%	≤ 1.0	
YSTE	Standard/Normal Illumination	Intensity	9118.0	W/m²	≥ 9000	
ILLUMINATION SYSTEM	L.I. ACCURACY		0.3	%	≤ 1.0	
NAT		θ	1818	ppm	≤ 3000	
M	MASKING BLADE ACCURACY	GZW	15	μm	≤ 60	
11		Total	55	μm	≤ ± 110	
		F(3σ)	0.039	μm	3σ ≤ 0.08	
	FOCUS - TILT STABILITY	Χ(3σ)	1.397	nnm	3 6	
		Υ(3σ)	2.755	ppm	3σ ≤ 6	
		F(3σ)	0.068	μm	3σ ≤ 0.10	
Ψ	FOCUS - TILT REPEATABILITY	Χ(3σ)	2.4	nnm	3σ ≤ 7	
SYST		Υ(3σ)	3.2	ppm		
FOCUS TILT SYSTEM	GLOBAL - TILT MEASUREMENT REPEATABILITY	Χ(3σ)	0.4	nnm	3 4	
LSUS	GLOBAL - TILT MEASUREMENT REPEATABILITY	Υ(3σ)	0.4	ppm	3σ ≤ 4	
Š.	GLOBAL - TILT ACCURACY	Χ(3σ)	1.0	nnm	30 < 9	
	GLOBAL - TIET ACCORACT	Υ(3σ)	1.1	ppm	3σ ≤ 8	
	TILT SENSOR UNEVEN FOCUS (DxD ON)	v	0.0	ppm	≤ ± 4	
	UNEVEN FOCUS (TSOC) (DxD OFF)	v	0.3	ppm	≤ ± 6	
	ALFC MEASUREMENT REPEATABILITY	3σ	0.06	μm	3σ ≤ 0.10	
TVPA	TV DDE ALTONIMENT ACCURACY (DARK ETELD)	x	1.12		≤ 3.0	
2	TV PRE-ALIGNMENT ACCURACY (DARK FIELD)	Y	1.55	μm	\$ 3.0	
		Ortho	-0.10			
	XYSA	Scal X	0.05	ppm	≤ ± .5	
TAGE		Scal Y	0.08			
WAFER STAGE	STEPPING ACCURACY	XX (3σ)	0.031	μm	3σ ≤ 0.040	
WAF		ΥΥ(3σ)	0.024			
	STEPPING REPEATABILITY	Χ(3σ)	0.026	μm	3σ ≤ 0.035	
		Υ(3σ)	0.012	F		
SRC	SRC MEASUREMENT REPEATABILITY	3σ	0.26	ppm	3σ ≤ 0.5	

-		XL(3σ)	0.003		3σ ≤ 0.01	
RETICLE ALIGNMENT	ROC MEASUREMENT REPEATABILITY	YL(3σ)	0.001			
	ROC PIEASUREPIENT REPEATABLELTY	XR(3σ)	0.004	μm	30 2 0.01	
		YR(3σ)	0.001	Ī		
ETIC	RETICLE ROTATION ACCUARACY		0.000	μm	≤ ± 0.01	
~	RETICLE ROTATION REPEATABILITY		0.002	μm	≤ ± 0.02	
		Χ(3σ)	0.006			
	DLCC STARTLEDY (MODE 1)	Υ(3σ)	0.005	μm	3σ ≤ 0.030	
	BLCC STABILITY (MODE 1)	RNG(X)	0.008		B < 0.03	
		RNG (Y)	0.007	μm	Range ≤ 0.03	
		Χ(3σ)	0.007		3- < 0.030	
BASELINE	DI CC CTARTI ITY (MODE 2)	Υ(3σ)	0.004	μm	3σ ≤ 0.030	
BASE	BLCC STABILITY (MODE 2)	RNG(X)	0.012		Range ≤ 0.03 3σ ≤ 0.031	
_		RNG (Y)	0.005	μm		
		Χ(3σ)	0.005			
	BLCC STABILITY (MODE 4)	Υ(3σ)	0.005	μm		
		RNG(X)	0.006		Range ≤ 0.03	
		RNG (Y)	0.007	μm		
	ACA ACCURACY MODE 1 (Incl. + 25)	x	0.038			
ĒĀ	AGA ACCURACY MODE 1 (m + 3σ)	Y	0.027	μm	mean + 3σ < 0.05	
AUTO ALIGNMENT	ACA ACCURACY MODE 3 (I—I + 3=)	x	0.037	LUPO	mean + 3σ < 0.05	
O ALI	AGA ACCURACY MODE 2 (m + 3σ)	Y	0.036	μm		
AG.	AGA ACCURACY MODE 4 (m + 3σ)	X	0.044	11170	1 1.5- 5	
	AGA ACCORACT MODE 4 (IIII + 30)	Y	0.035	μm	mean + 3σ < 0.05	
~		θ	3.92	μm	3σ ≤ 30	
EDE		XL	6.289			
WAFER REDER	WAFER FEEDER ADJUSTMENT ACURACY (MECH PA)	XR	6.388	um	3σ ≤ 40	
NAFE		YL	18.21	μm	30 2 40	
		YR	5.951			
TPD	THROUGHPUT 6" WAFER TYPE-L WF	DxD ON	131.0	WPH	>102	
1110	THROUGHFUT O WAFER TIPE-L WF	DxD OFF	129.4	WFII	>102	
	WAFER CHUCK FLATNESS	□ 22mm		μm		

Photos to Collect

- All 4 sides
- Loader
- Chuck
- Cameras
- Control panel
- Chamber
- Robot
- Inside all of the cabinets (PCB's)
- Electronic racks (inside the boards as well)
- All electronic in/outlets
- Serial plate
- Spare parts, manuals (if any)



MODEL	FPA-3000 i5	INSTALLATION CHECK LIS		
SN	7122157	INSTALLATION CHECK LIST		
CUSTOMER	ON Semi	STEPPER NAME STEPPER		

	DESCRIPTION		Results	UNIT	SPECIFICATION	
	LENC DICTORTION (NUCS-CE)	DX	0.034		c 1 0 0 4	OK.
NOI	LENS DISTORTION (NA63065)	DY	0.029	μm	≤ ± 0.04	OK
	LENS DISTORTION Special Mode 1	DX	0.041			NA
TOR		DY	0.057	μm	NA	
LENS DISTORTION	LENS DISTORTION	DX	0.043		NA	NA
LENS	Special Mode 2	DY	0.064	μm	NA NA	NA
_	LENS DISTORTION	DX	0.024		NA	NA
	Special Mode 4	DY	0.032	μm	NA.	NA
		Initial	0.00			
	SP1	Heated	-0.05		B 4 B 211	ок
	NA0.5200.60	Cooled	0.05	μm	Range < 0.3μm	
		Range	0.10			
EXPOSURE FOCUS STABILITY	SP2 NA0.55σ0.50	Initial	0.00		Range < 0.3mm	
Sno		Heated	0.10			ok
8		Cooled	0.15	μm		OK
SUR		Range	0.15			
8 8	SP4 NA0.63σ0.70	Initial	0.05	μm	Range < 0.3µm	ок
-		Heated	0.05			
		Cooled	0.00			
		Range	0.05			
		Initial	3.22		Range < 2.0 ppm	
>	SP1 NA0.52σ0.60	Heated	2.61	ppm		ок
		Cooled	3.52	PP		
STAE		Range	0.92			
EXPOSURE MAGNIFICATION STABILITY		Initial	3.32			
IGA	SP2	Heated	3.25	ppm	Range < 2.0 ppm	ок
GNIF	NA0.55σ0.50	Cooled	3.77	,,,,,,		- N
MA		Range	0.51			
SUR		Initial	3.34			
0 A	SP4	Heated	3.22	ppm	Range < 2.0 ppm	ок
	NA0.63σ0.70	Cooled	2.77	P-P-III		OK.
		Range	0.57			

	Second and Manager I Thomas a single	Uniformity	1.6	%	≤ 1.0	
	Standard/Normal Illumination	Intensity	8235.0	W/m²	≥ 9000	NG
	Special Illumination Mode 1	Uniformity	1.7	%	NA	
Σ		Intensity	11478	W/m²	NA	NG
YSTE		Uniformity	2.1	%	NA	NG
S NO	Special Illumination Mode 2	Intensity	11908	W/m²	NA	NG
Ē	Control Wheelers Made 4	Uniformity	1.3	%	NA	NG
ILLUMINATION SYSTEM	Special Illumination Mode 4	Intensity	10890	W/m²	NA	NG
⊒	LI ACCURACY		0.45	%	≤ 1.0	ок
		θ	-113.6	ppm	≤ 3000	
	MASKING BLADE ACCURACY	GZW	20	μm	≤ 60	ок
		Total	32.5	μm	≤ ± 110	
	FOCUS - TILT STABILITY	F(3σ)	0.038	μm	3σ ≤ 0.08	
		Χ(3σ)	2.909	ppm	3σ ≤ 6	OK
		Υ(3σ)	2.754			
	FOCUS - TILT REPEATABILITY	F(3σ)	0.08	μm	$3\sigma \le 0.10$	
Σ		Χ(3σ)	2.7		3σ≤7	ок
SYST		Υ(3σ)	3.8	ppm	30 2 7	
II.	GLOBAL - TILT MEASUREMENT REPEATABILITY	Χ(3σ)	0.6		3σ ≤ 4	ОК
FOCUS TILT SYSTEM	SESSIVE - HET PERSONEPIENT REPEATABLETT	Υ(3σ)	0.7	ppm	3	UK.
Š	GLOBAL - TILT ACCURACY	Χ(3σ)	1.8	ppm	3σ ≤ 8	ОК
	despite The Accorder	Υ(3σ)	1.0	ppiii	38.40	OK
	TILT SENSOR UNEVEN FOCUS (DxD ON)	v	0.0	ppm	≤ ± 4	ок
	UNEVEN FOCUS (TSOC) (DxD OFF)	V	1.5	ppm	≤ ± 6	ОК
	ALFC MEASUREMENT REPEATABILITY	3σ	0.03	μm	3σ ≤ 0.10	OK
IVPA	TV PRE-ALIGNMENT ACCURACY (DARK FIELD)	X	1.94	μm	≤ 3.0	ОК
4	THE PLOTTER ACCOUNT (CAR FIELD)	Υ	2.55	μ	3 310	OK

	XYSA	Ortho	-0.05			OK
		Scal X	0.01	ppm	≤ ± .5	
		Scal Y	-0.03			
		XX (3σ)	0.011			
		ΧΥ (3σ)	0.011		3σ ≤ 0.040	
	STEPPING ACCURACY WAFER 1	ΥΧ (3σ)	0.011	μm		OK
		ΥΥ(3σ)	0.014			
AGE		XX (3σ)	0.010			
R ST		XY (3σ)	0.009	Ī		
WAFER STAGE	STEPPING ACCURACY WAFER 2	ΥΧ (3σ)	0.015	μm	3σ ≤ 0.040	OK
>		ΥΥ(3σ)	0.015	Ī		
		XX (3σ)	0.011			
	STEPPING ACCURACY WAFER 3	ΧΥ (3σ)	0.009	İ	3σ ≤ 0.040	
		ΥΧ (3σ)	0.014	μm		OK
		ΥΥ(3σ)	0.011	1		
	STEPPING REPEATABILITY	Χ(3σ)	0.023			
		Υ(3σ)	0.013	μm	3σ ≤ 0.035	OK
SRC	SRC MEASUREMENT REPEATABILITY	3σ	0.30	ppm	3σ ≤ 0.5	ОК
_	ROC MEASUREMENT REPEATABILITY	XL(3σ)	0.004	μm	3σ ≤ 0.01	ок
Ä.		YL(3σ)	0.002			
8		XR(3σ)	0.005			
E AI		YR(3σ)	0.002			
RETICLE ALIGNMENT	RETICLE ROTATION ACCUARACY		-0.003	μm	≤ ± 0.01	ок
~	RETICLE ROTATION REPEATABILITY		0.001	μm	≤ ± 0.02	ок
		Χ(3σ)	0.005		3- 40030	CH.
	DIC CTARTITO (MODE 4)	Υ(3σ)	0.008	μm	3σ ≤ 0.030	OK
	BLC STABILITY (MODE 1)	RNG(X)	0.007		D	
		RNG (Y)	0.012	μm	Range ≤ 0.03	OK
		Χ(3σ)	0.005		2- < 0.020	CW.
¥.	DIG CTARRIETY (MORS 2)	Υ(3σ)	0.004	μm	3σ ≤ 0.030	OK
BASELINE	BLC STABILITY (MODE 2)	RNG(X)	0.006			
		RNG (Y)	0.006	μm	Range ≤ 0.03	OK
		Χ(3σ)	0.007		2- 40024	
	DIG CTION TO (MODE 1)	Υ(3σ)	0.006	μm	3σ ≤ 0.031	OK
	BLC STABILITY (MODE 4)	RNG(X)	0.009	μm		OK
		RNG (Y)	0.008		Range ≤ 0.03	
	I					

ENT	AGA ACCURACY MODE 1 (m + 30)	X	0.023		mean + 3σ < 0.05	ok
		Y	0.026	μm		
AUTO ALIGNMENT	AGA ACCURACY MODE 2 (m + 30)	x	0.035	μm	mean + 3σ < 0.05 mean + 3σ < 0.05	
] ALI		Y	0.027			OK
AGT	ACA ACCIDACY MODE 4 (Incl. + 3cr.)	X	0.024			ок
	AGA ACCURACY MODE 4 (m + 3σ)	Y	0.031	μm		OK
		XL	5.796	μm	3σ ≤ 40	ок
		XR	6.016			
		YL	8.58			
		YR	7.315			
TPD	THROUGHPUT 6" WAFER TYPE-L WF	DxD ON	128.5	WPH	>120	OK
170	THROUGHFUT WATER TIPE WE	DxD OFF	130.1		>120	OK
	WAFER CHUCK FLATNESS	□ 22mm	0.44	μm		